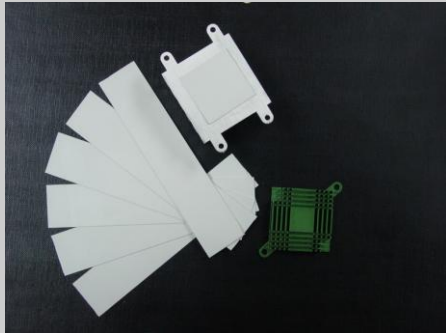


HIGHLY COMPRESSIBLE GAP FILLER 3.2W/m-K

Features and Benefits

- 3.2W/m-K thermal conductivity
- Superior compressibility
- RoHS compliant
- Halogen-free
- Naturally tacky
- Electrically isolating



Typical Applications

- Notebook Computers
- Handheld Portable Electronics
- Micro Heat Pipe assemblies
- Micro Processors, Memory Chips and Graphic Processors
- Motor Control
- Wireless Communication Hardware

Optional Configurations

- Can be die-cut into specific dimensions

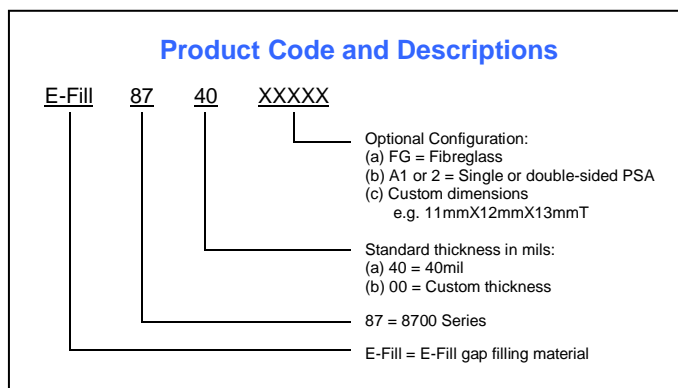
E-Fill 8700 has good thermal performance and is highly compressible. It can blanket highly uneven surfaces and is suitable for applications where low applied pressure is required.

Its RoHS compliant and halogen-free status provides extra assurance for applications that are sensitive to hazardous substances.

In addition, E-Fill 8700 is electrically non-conductive and naturally tacky. Additional adhesive coating is generally not required.

Properties	E-Fill 8700 Series	Test Method
Construction & Composition	Reinforced Soft silicone elastomer	—
Color	White	Visual
Thickness Range /inch (mm)	0.02"~0.40" (0.254~10.16) in 0.01" (0.254) increments	—
Standard Sheet Size	12" x 16"	—
Density /g.cm ⁻³	1.36	—
Hardness /Shore 00	45	ASTM D2240
Temperature Range /°C	-40~200°C	—
Thermal Conductivity /W.m ⁻¹ .K ⁻¹	3.2	ASTM D5470 (modified)
Breakdown Voltage /V	>3000 (Thickness ≤ 0.02") >5000 (Thickness = 0.03~0.05")	ASTM D149
Shelf Life	24 months	—
Please contact us for other special requirements		

Carrier Treatment	Criteria
Fiber Glass (FG)	Compulsory for all thickness
Rubberized Cloth (RC)	Not Recommended
Pressure Sensitive Adhesive (PSA)	Not Recommended
Detachable Adhesive (DA)	Not Recommended
Aluminum Foil (AL)	Not Recommended
Kapton (PI)	Not Recommended
Talc treatment (DAT)	Not Recommended



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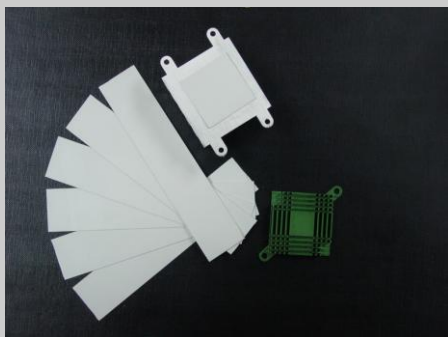
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产品特点

- 导热率 3.2W/m-K
- 高压缩比
- 符合 RoHS 规格
- 无卤素
- 具有天然粘性
- 电绝缘



一般应用

- 电子笔记本
- 手提电子器材
- 微热管组件
- 微处理器，内存芯片，图形处理器
- 底盘，框架或其他散热组件
- 电机控制器
- 通信用硬件

其他配置

- 可模切成特定尺寸

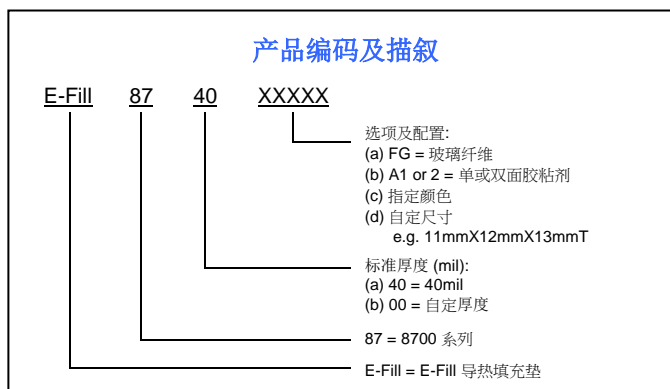
E-Fill 8700 是一种能够提供良好表面吻合度的高性能导热填充垫。它能够有效地覆盖热源及散热器不平的表面而达到热传导效果。

独有的产品配方不单指符合 RoHS 规格更达到无卤素要求，令客户在使用时对于有害物质的控制更有信心。

Fill 8700 具有电绝缘及天然粘性等特点，在正常情况下不需要增加额外的胶粘剂。

一般特性	E-Fill 8700 系列	测试方法
结构及主要成分	物理强化硅树脂弹性体	—
颜色	白色	目测
厚度 /inch (mm)	0.02"~0.40" (0.254~10.16) 以 0.01" (0.254)为基本增量单位	—
标准片材尺寸	12" x 16"	—
密度 /g.cm ⁻³	1.36	—
硬度 /Shore 00	45	ASTM D2240
使用温度 /°C	-40~200°C	—
导热率 W.m ⁻¹ .K ⁻¹	3.2	ASTM D5470 (modified)
击穿电压/V	>3000 (厚度 ≤ 0.02") >5000 (厚度 = 0.03~0.05")	ASTM D149
有效期	24 months	—
如对产品有特殊要求，请联络我们		

载体	Criteria
玻璃纤维 (FG)	任何厚度必须使用
胶布 (RC)	不建议使用
压敏胶 (PSA)	不建议使用
不粘胶 (DA)	不建议使用
铝箔 (AL)	不建议使用
聚酰亚胺膜 (PI)	不建议使用
滑石粉处理 (DAT)	不建议使用



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东莞

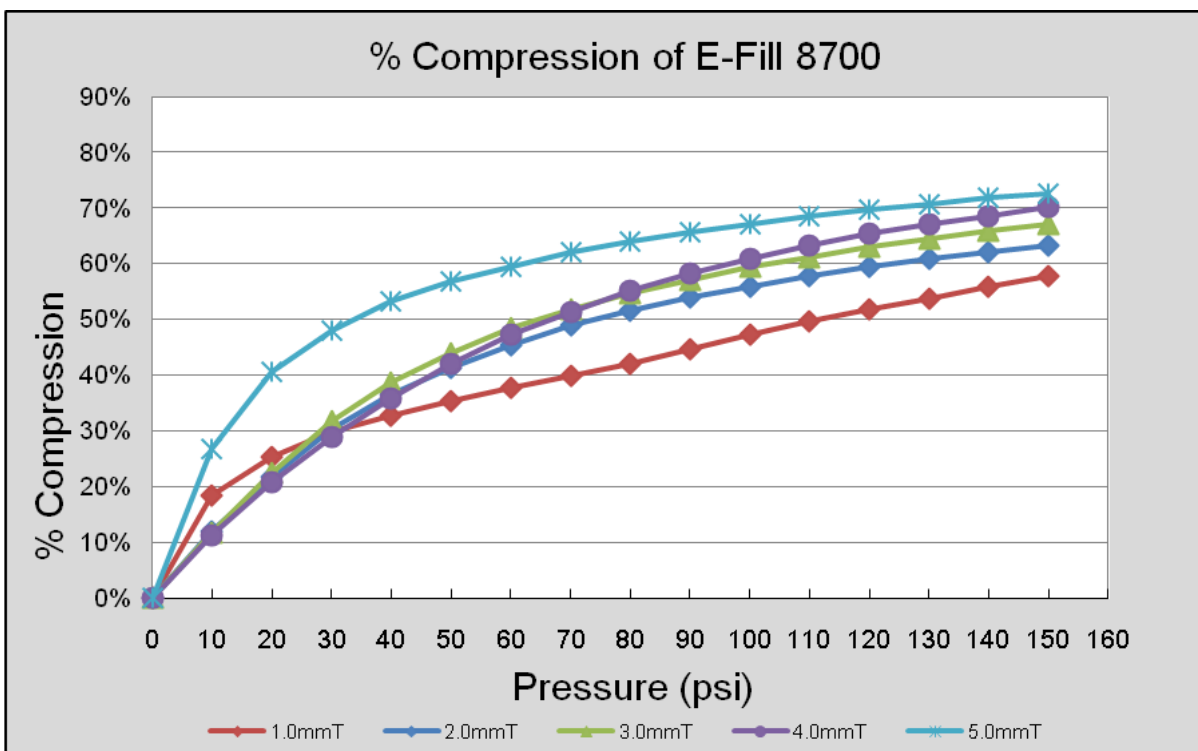
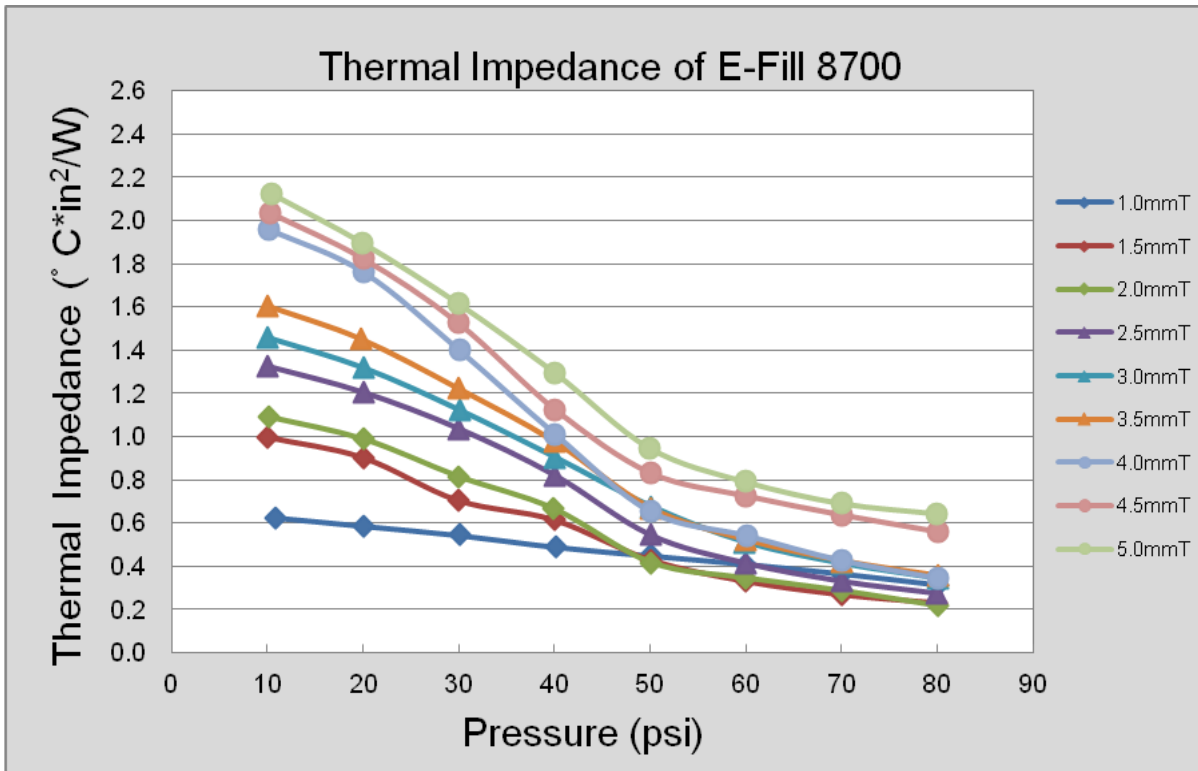
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